



Advance Product Change Notification

201305008A

Issue Date: 09-Jun-2013

Here's your personalized quality information concerning products from NXP.

For detailed information we invite you to [view this notification online](#)



QUALITY

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire material from gold to copper in SOT23 package

Details of this Planned Change

Scheduled changes affect product types in SOT23 package only.
The bond wire material will be changed from gold to copper.

Old product: Wire material is gold (Au)

Changed product: Wire material is copper (Cu)

Only the wire material is changed. The design and materials of all other components will remain unchanged: mold compound, die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature are performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Plan this Change

Aligning with world technology trends, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

Identification of Affected Products

Copper wire products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 01-Nov-2013

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201005007F	27-Aug-2010		Change of bond wire material from gold to copper in SOT23 package
201011012F	13-Dec-2010		Change of bond wire material from gold to copper in SOT23 package and 8 inch wafer diameter
201106020F0114	14-Aug-2011	07-Nov-2011	Change of bond wire material from gold to copper in SOT23 package

Timing and Logistics

The Self Qualification Report will be ready on 25-Jun-2013.

The Final PCN is planned to be issued on: 15-Jul-2013.

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 09-Jul-2013.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support
e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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